

A 65nm Dual-mode Baseband and Multimedia Application Processor SoC with Advanced Power and Memory Management

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Outline

1. Introduction

2. Chip Architecture

3. Power Management

- Static Power (Hierarchical Power Domain)
- Dynamic Power (Partial Clock Activation)

4. Memory Management

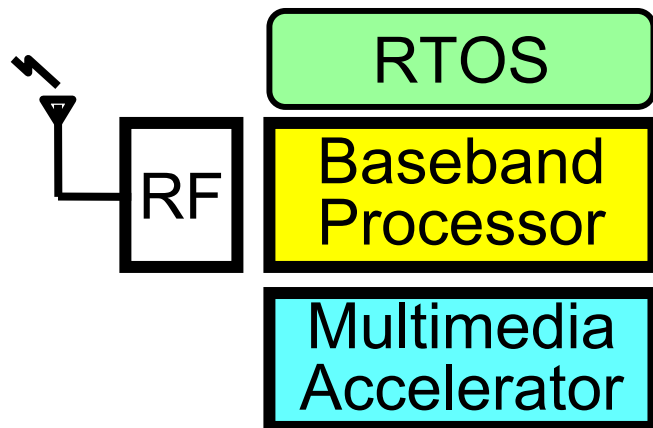
- IP-MMU

5. Summary

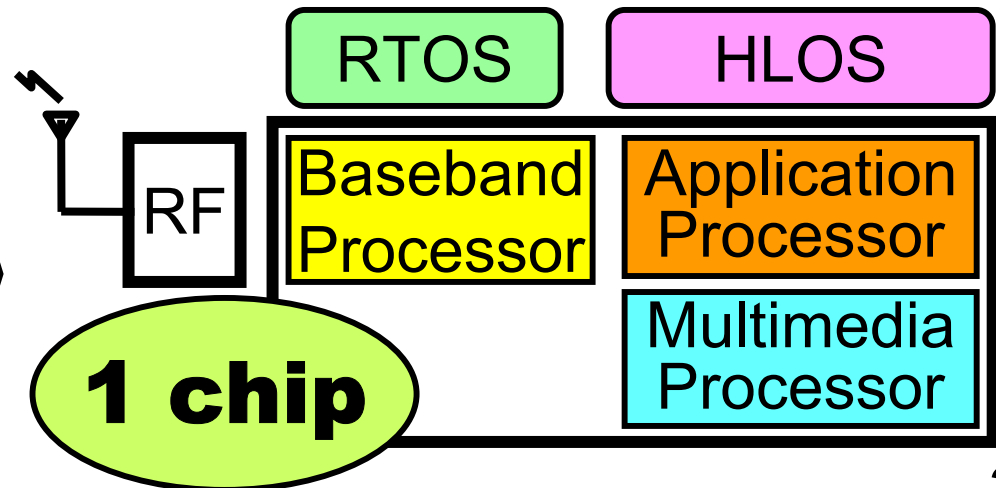
Introduction(1) Trend of Mobile phone

- In a 2G handset, a baseband processor executed applications in addition to modem control. (RTOS)
- In a high-end 3G handset, applications require High-Level-OS and rich multimedia functions. 3(BB, AP, and MM) processors in a handset.
- System cost increase → **1 chip integration**

2G (Conventional)



3G system



Introduction(2) Challenges

- **Low Power**

- Limited battery capacity
- No fan

- **High Performance**

- Digital TV
- Mega-pixel camera
- 3D graphics for games and UI

- **System Cost**

- Memory capacity (SDRAM, NAND/NOR FLASH)
- Packaging (SIP, POP)

Introduction(3) History of SH-Mobile G

- **1st generation SH-Mobile G1**

- In mass production from 2006. 8
- 141M Transistors, 90nm LP
- Hierarchical Power Domain for leakage reduction

- **2nd generation SH-Mobile G2**

- In mass production from 2007. 8
- 249M Transistors, 90nm LP
- Inter-Connect Buffer for high-performance multimedia

- **3rd generation SH-Mobile G3**

- In mass production from 2008. 8
- 307M Transistors, 65nm LP
- Partial Clock Activation for dynamic power reduction
- IP-MMU for memory footprint reduction

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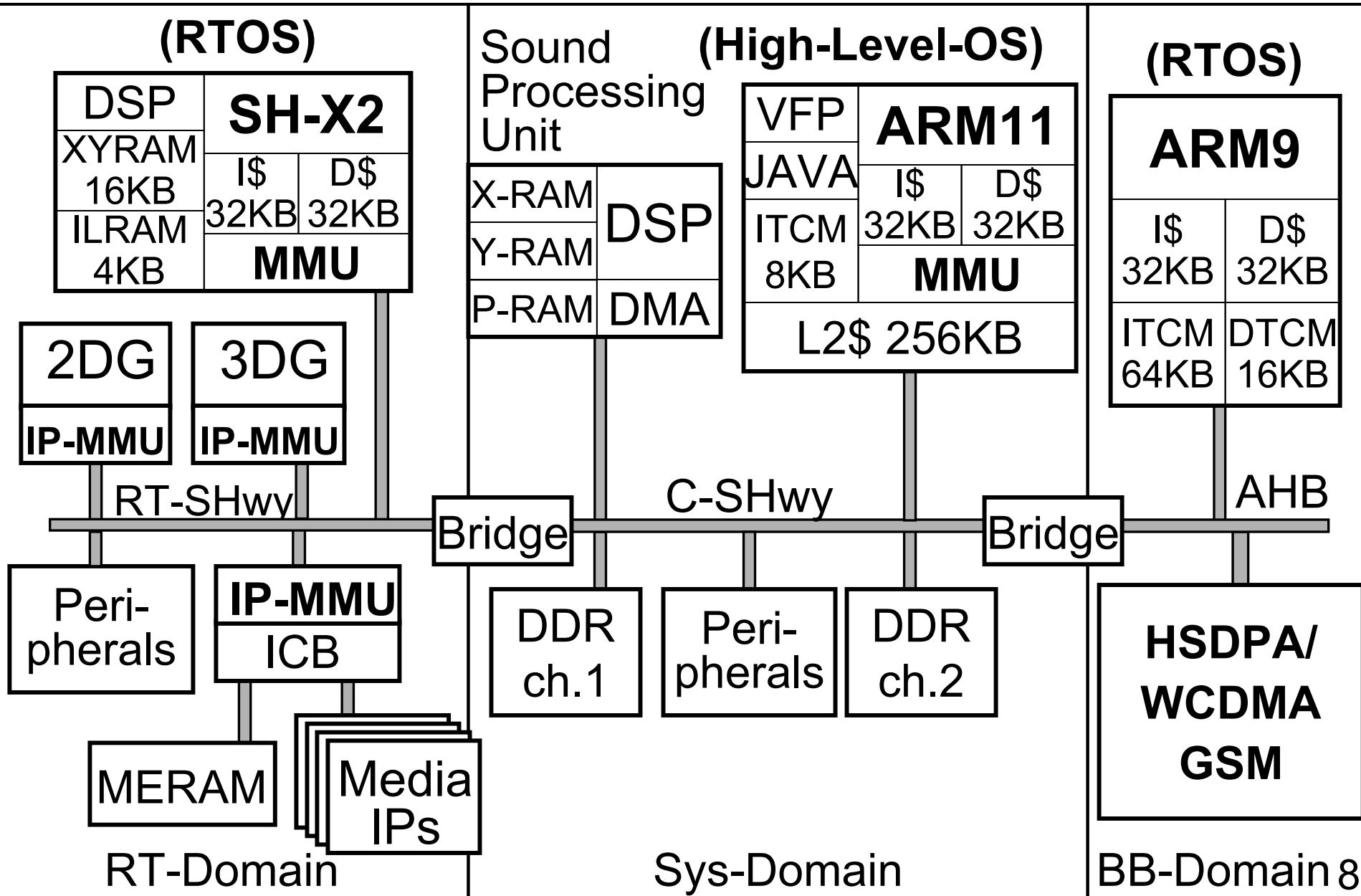
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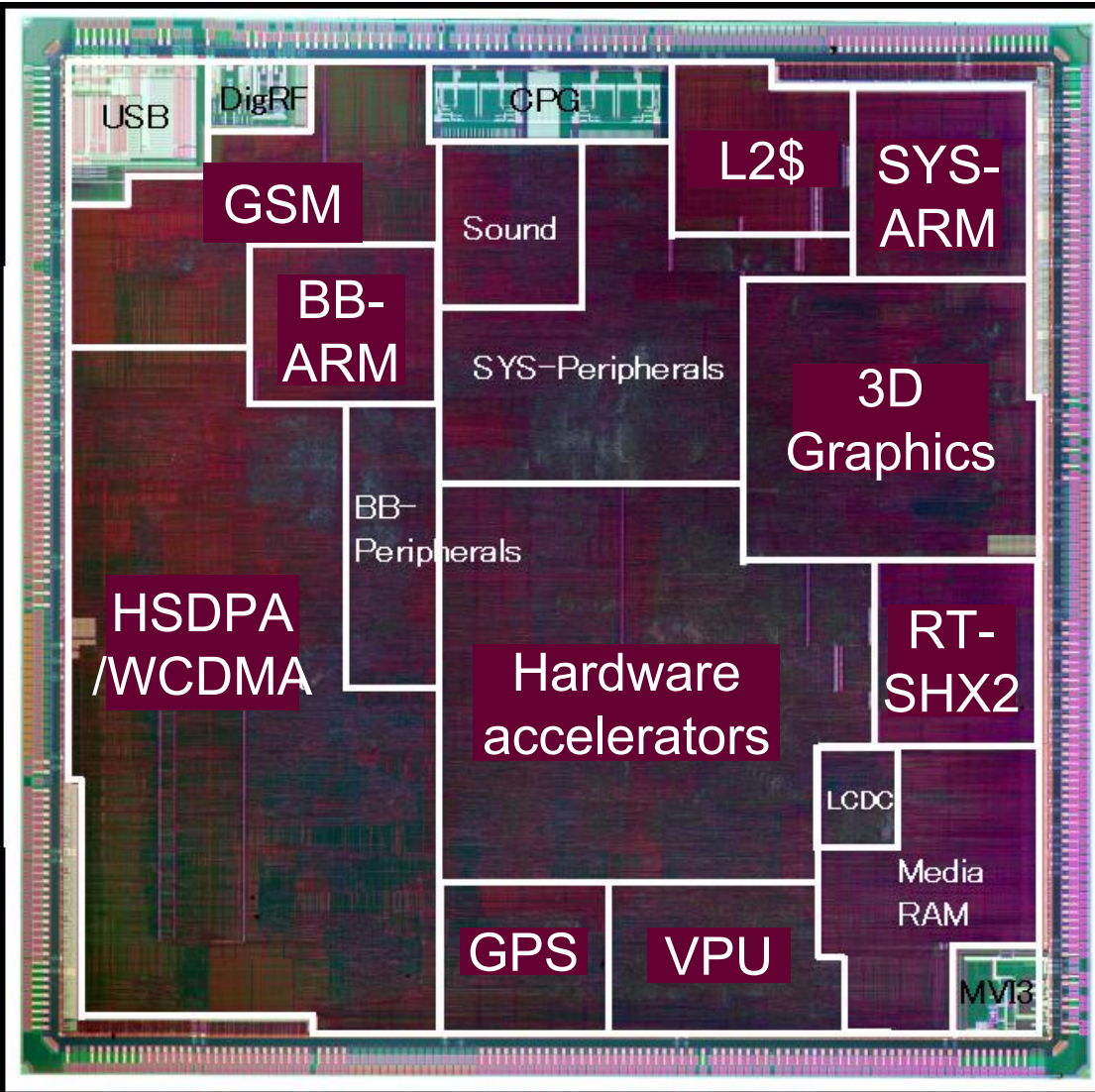
SH-Mobile G3 Chip Specifications

CPU	ARM926EJ-S, 166MHz [baseband] ARM1176JZF-S, 500MHz [application] SH-X2, 500MHz [multimedia]
3G/2G modem	W-CDMA/HSDPA Cat. 8 (up to 7.2 Mbps), GSM/GPRS/EDGE
Multimedia hardware engines	Video Processing Unit(VPU) (MPEG4/H.264/VC-1 D1 size), Sound Processing Unit(SPU), 3D/2D Graphics, GPS, LCDC, Camera interface (up to 12M pixels), 512KBytes MediaRAM(MERAM)
I/O	617 pins

Block Diagram (Bus Architecture)



Die micrograph



Die size	9.3mmx9.3mm
Process	65nm LP 8M(7Cu+1Al) 3Vth CMOS
Supply voltage	1.2V(internal), 1.8/2.5/3.3V (I/O)
# of TRs, gate, memory	307M TRs (28.2M Gates, 30.7Mb RAM, 6.4Mb ROM)

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Power Management

Both Static and Dynamic Power are very important for mobile application!

- Static Power Consumption (Leakage)

Objective: Standby time

Technique: Hierarchical Power Domain (HPD)

- Dynamic Power Consumption

Objective: Operational time

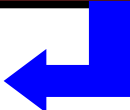
Technique: Partial Clock Activation (PCA)

Static Power Management

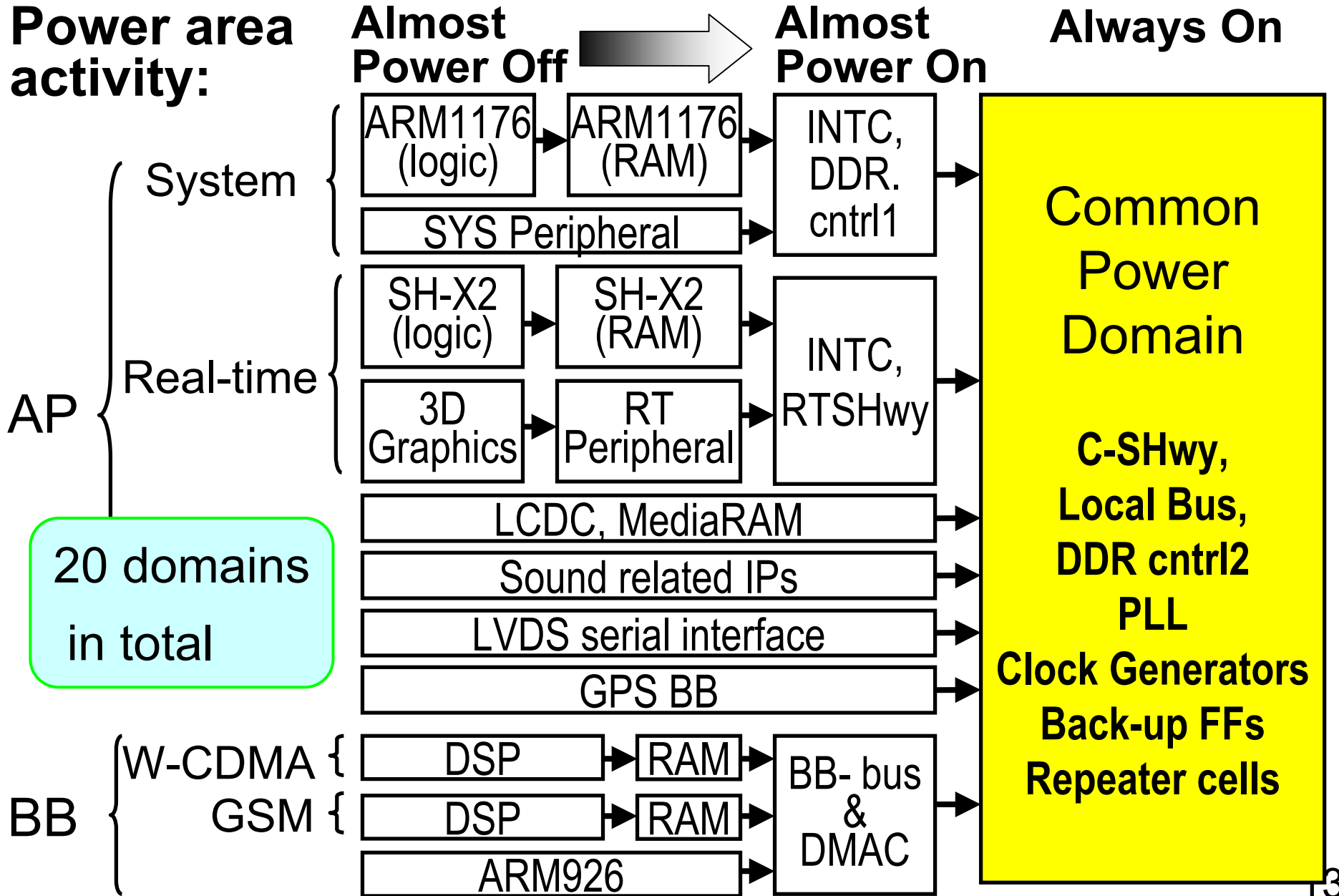
Tr. Vth	Leakage	Frequency
HVth	Good (Low)	Poor (Low)
MVth	Moderate	Moderate
LVth	Poor (High)	Good (High)

- Triple Vth technology
- Power Domain Separation (Partial Power-Off)

# of domains	Pros	Cons
Few	Easy to control	Limited Leakage reduction
Many	Optimal Leakage reduction	Difficult to control

Hierarchical Power Domain (HPD) 

Hierarchical Power Domain



Hierarchical Power Domain

Power area activity:

Almost Power Off



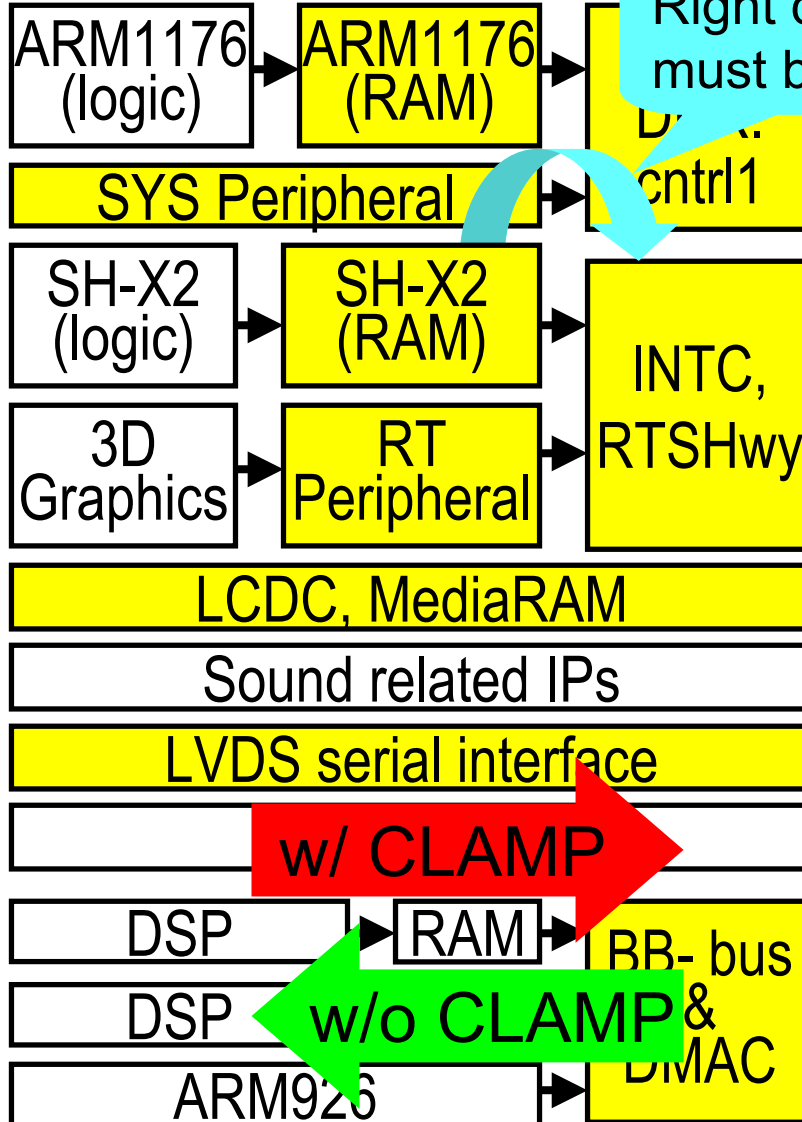
Almost Power On

Always On

System {
Real-time {
AP {

20 domains in total

BB {
W-CDMA {
GSM {



Right domain must be ON

Common Power Domain

**C-SHwy,
Local Bus,
DDR cntrl2
PLL**

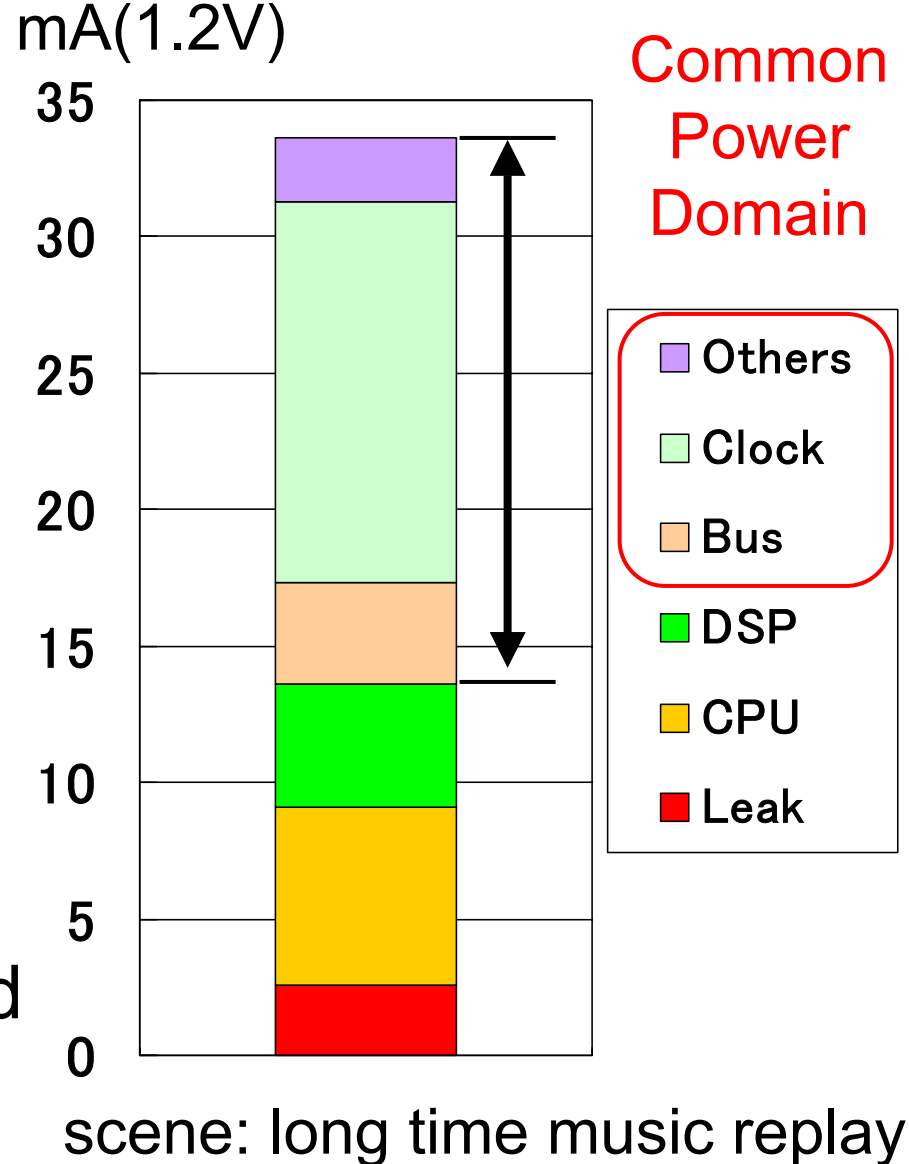
**Clock Generators
Back-up FFs
Repeater cells**

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Dynamic Power Management

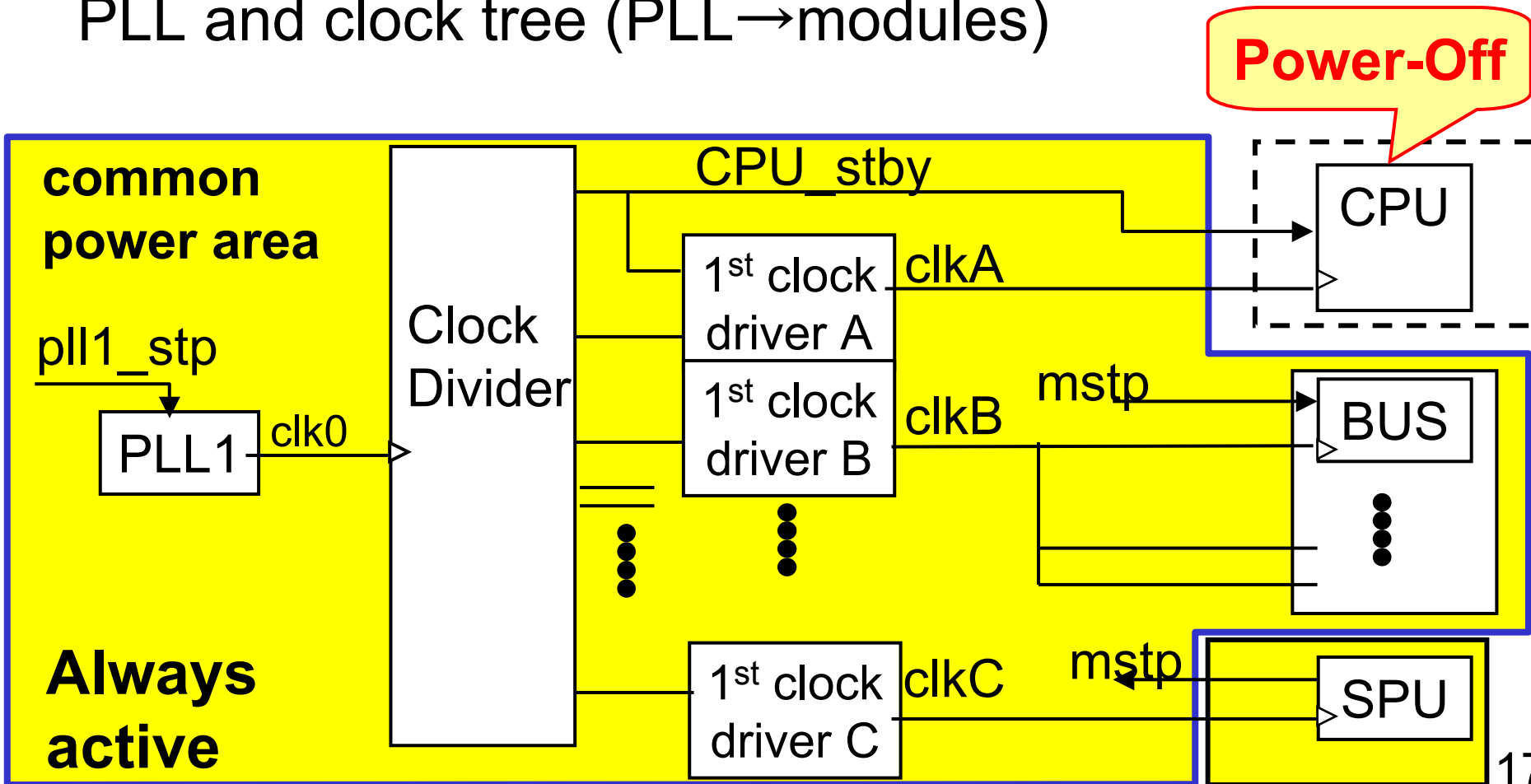
- At low power scenario (music replay etc.), estimated power would go over the budget.
- all un-used domains already in power-off
- Clock gating already applied deeply
- In this case, Common Power Domain consumed large percentage of whole chip power (60%).



Partial Clock Activation: Motivation

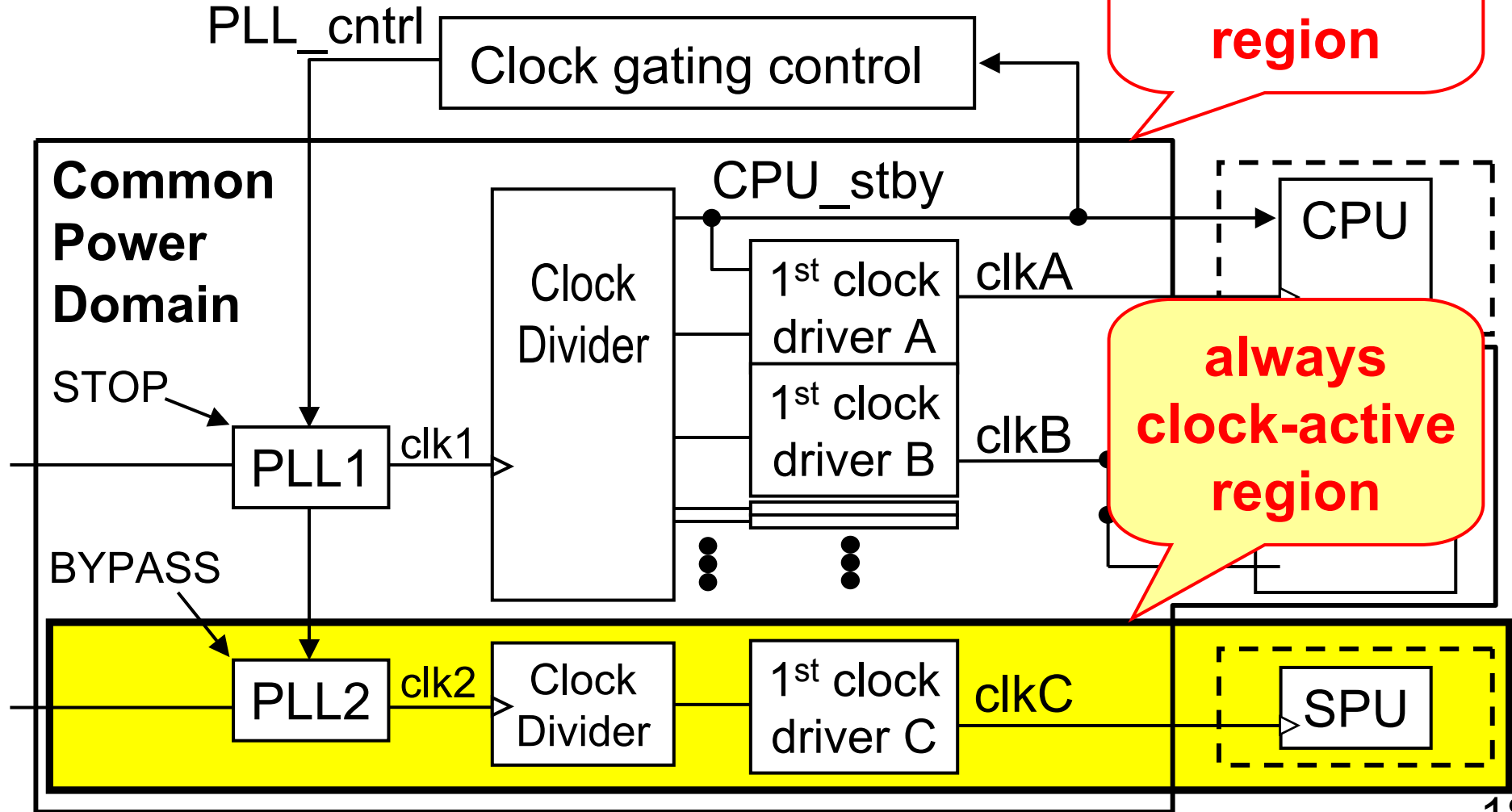
[Problem cause]

- Big modules have already been in power-off.
- But accumulated “small” power is not negligible.
PLL and clock tree (PLL→modules)



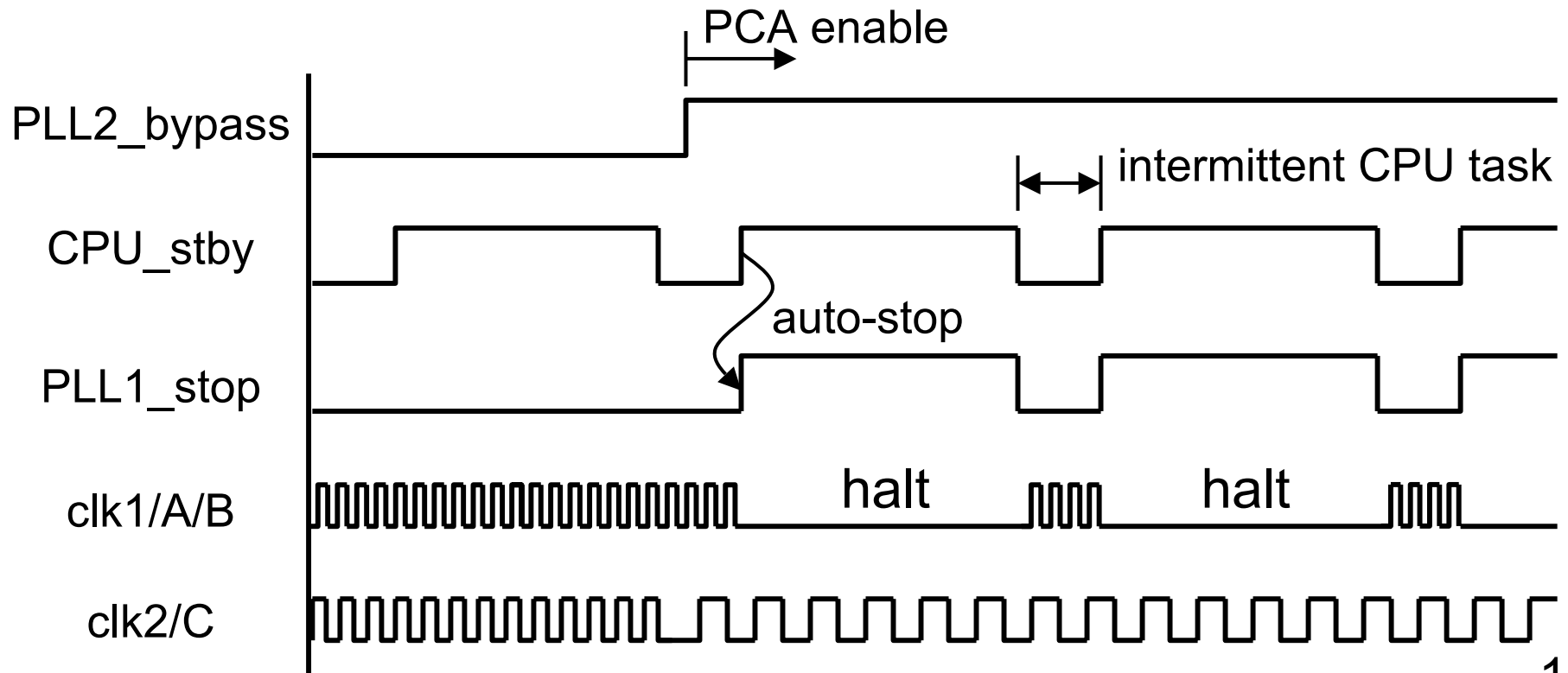
Partial Clock Activation: Diagram

- Clock tree separation
- Intermittent activation



Partial Clock Activation: Control

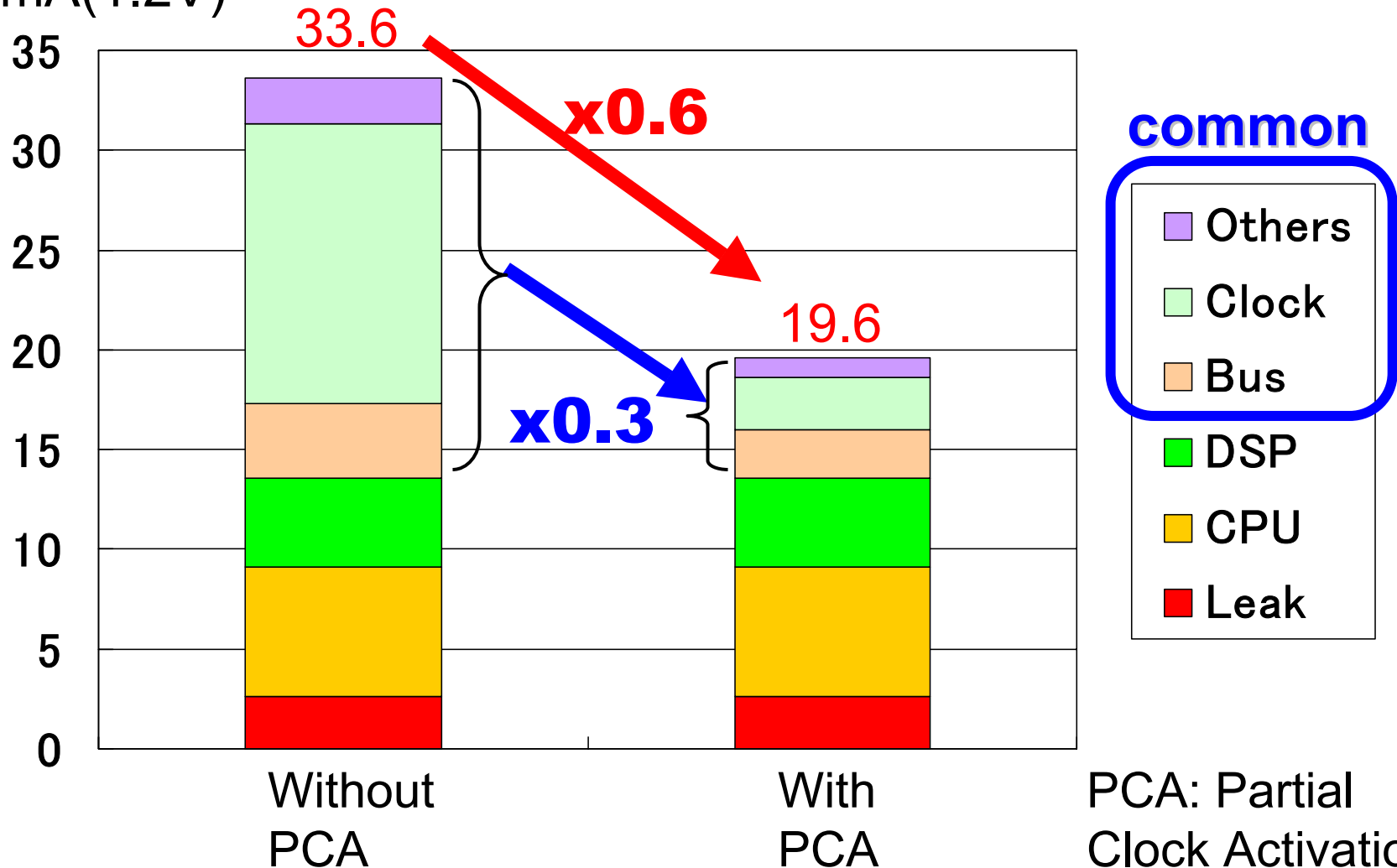
- Clock for SPU and serial IO is slowed down (PLL2 is bypassed.)
- PLL1 and clock tree is stopped in synchronization with CPU stand-by. They are reactivated in intermittent manner for housekeeping operation. (data copy from SD-card to SPU)



Partial Clock Activation: Result

Scene: Long time music replay

mA(1.2V)



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Memory Management: Motivation

In general, efficient memory management is required for mobile phone due to limited memory capacity.

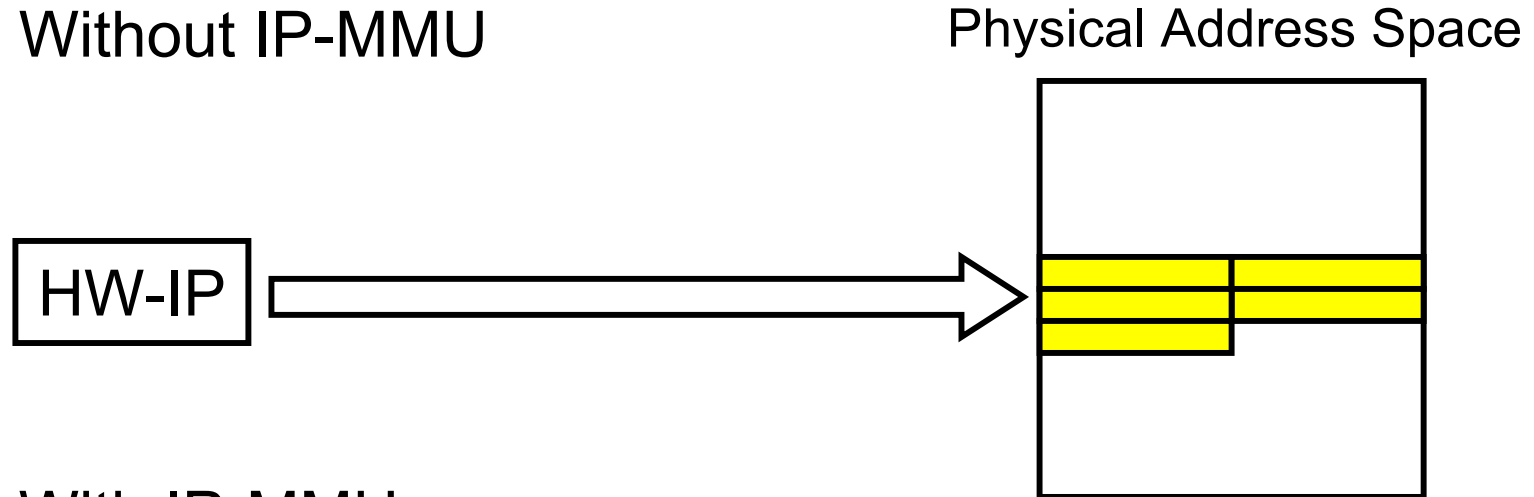
Goal: To reduce system cost by minimizing memory footprint

However,

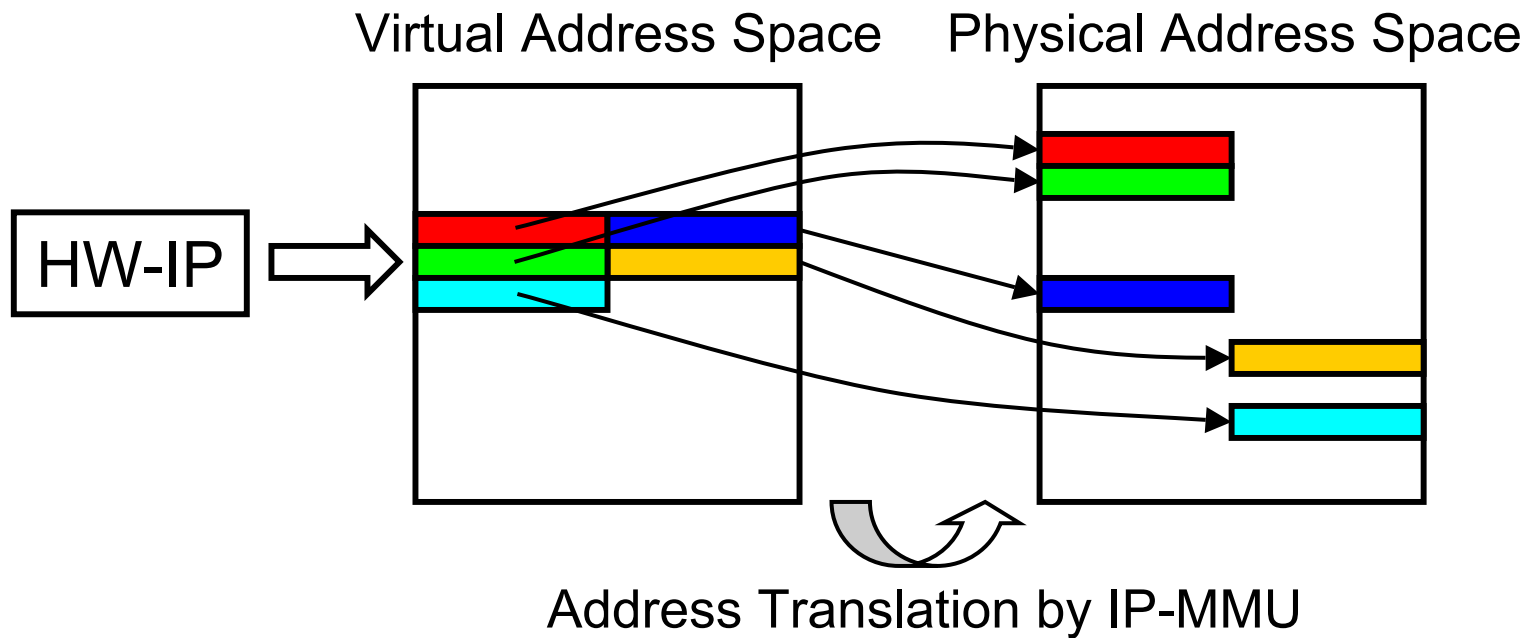
1. HW-IP (Accelerator) requires **address-contiguous** large memory regions.
2. **Memory fragmentation** proceeds with application execution. Large memory chunk may not remain after some applications have run (even after exit)!
3. To avoid this fragmentation, large memory regions have to be **statically** allocated **at boot phase** .
4. As a result, system footprint on main memory becomes very large although **actual memory size in use at the same time is not so large!**

IP-MMU: Concept

(a) Without IP-MMU



(b) With IP-MMU



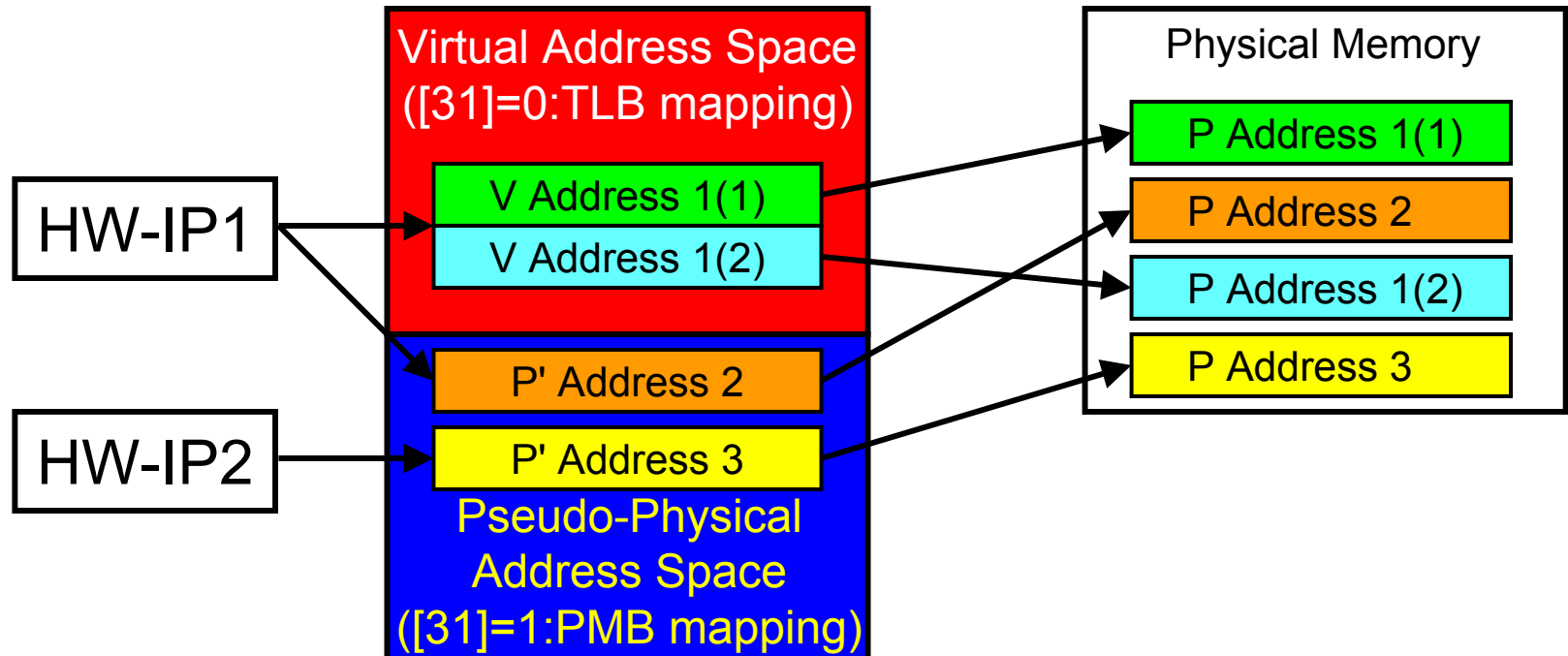
IP-MMU: Benefit

Benefit

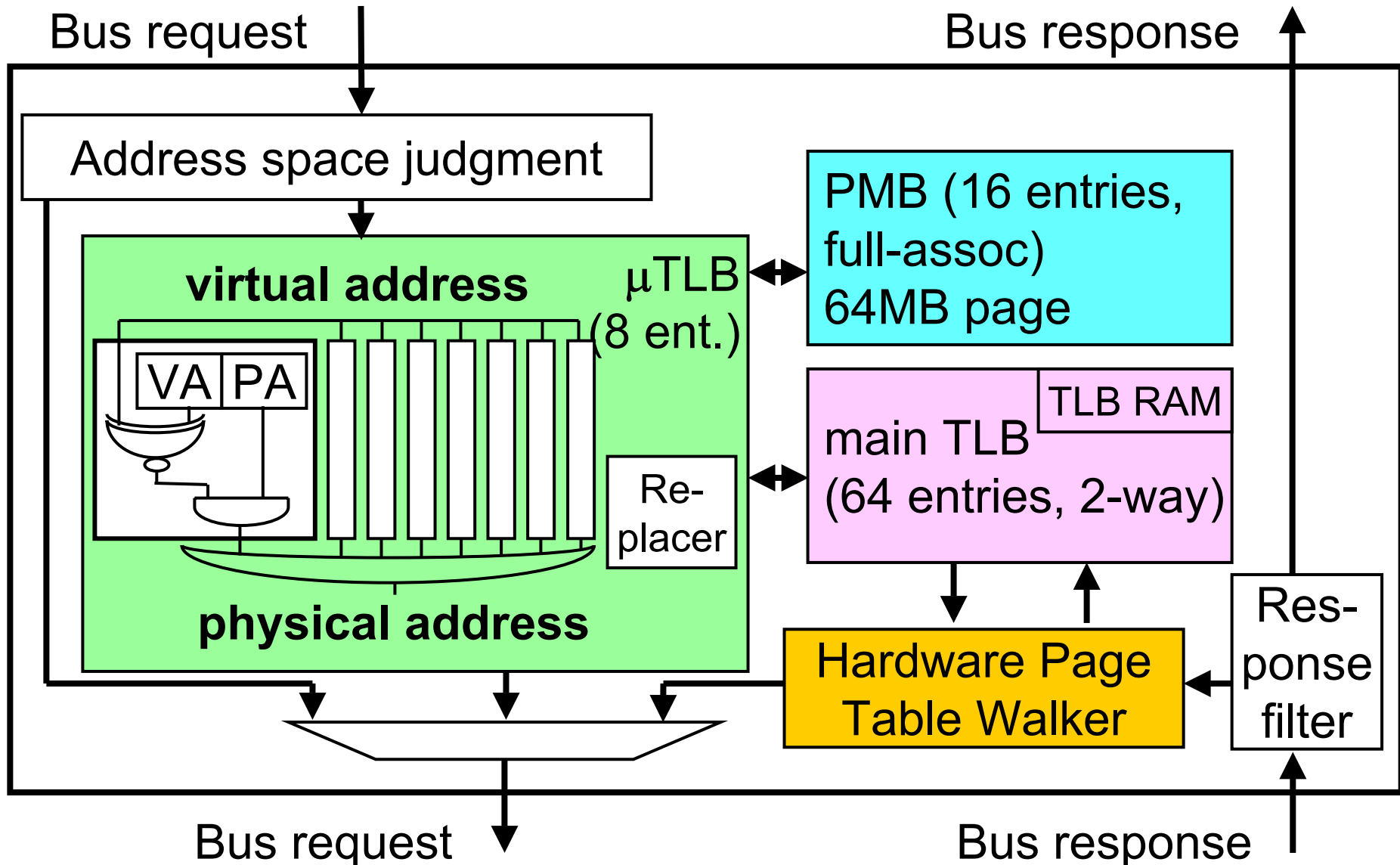
- Large address-contiguous memory regions can be composed of physically fragmented memory chunks.
Memory regions can be freed after applications terminated and they can be allocated on demand.
Reduction of system footprint
- HW-IP can see Virtual Address Space like CPU.
CPU and HW-IPs can directly share the "pointer" to the memory.
Easy development of applications utilizing HW-IPs

IP-MMU : Address Space View

- First half (2GB): TLB (Translation Look-aside Buffer)
 - Dynamically allocated by OS (4KB granularity)
 - Shared with a software process on OS
- Second half (2GB): PMB (Physical-address Mapping Buffer)
 - Statically allocated at boot time (always alive)
(e.g. LCDC frame buffer)
 - Access window to arbitrary physical address



IP-MMU: Implementation (Basic)



IP-MMU: Problem

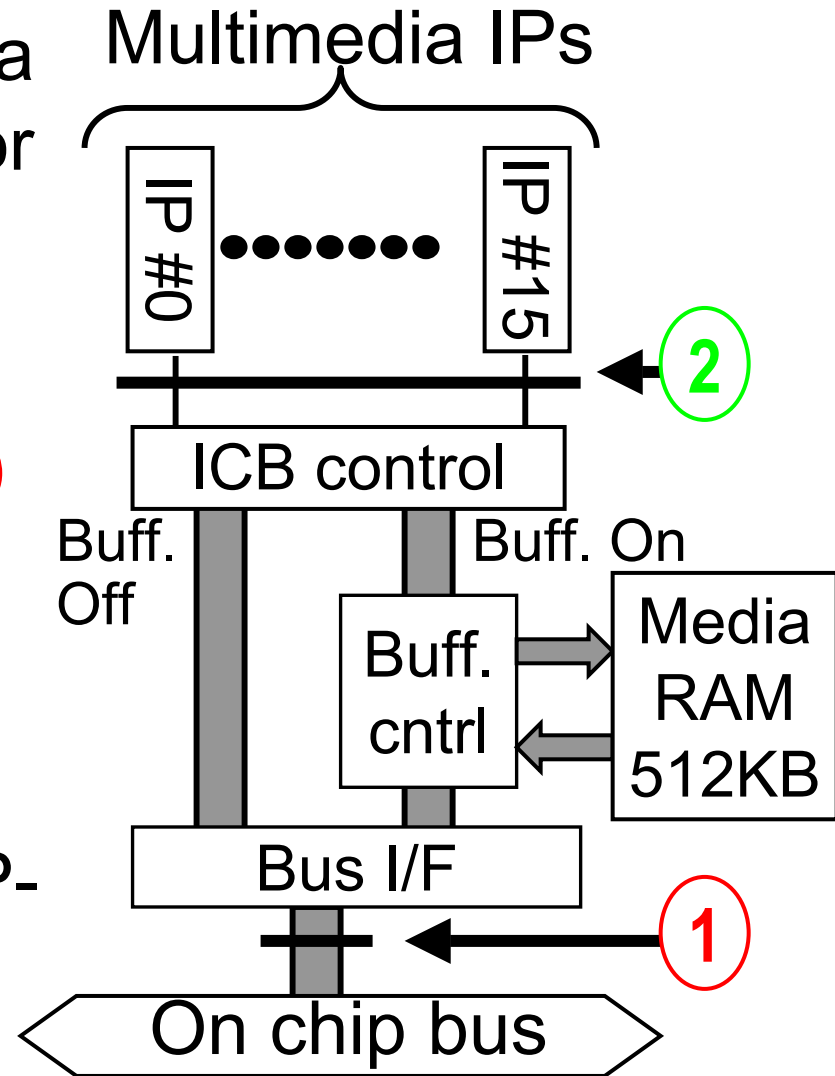
Inter-Connect Buffer (ICB) is the bus bridge that buffers data with 512 KBytes MediaRAM for inter-IP communication.

[Problem1]

Inserting IP-MMU at bus I/F ⁽¹⁾ may degrade performance.

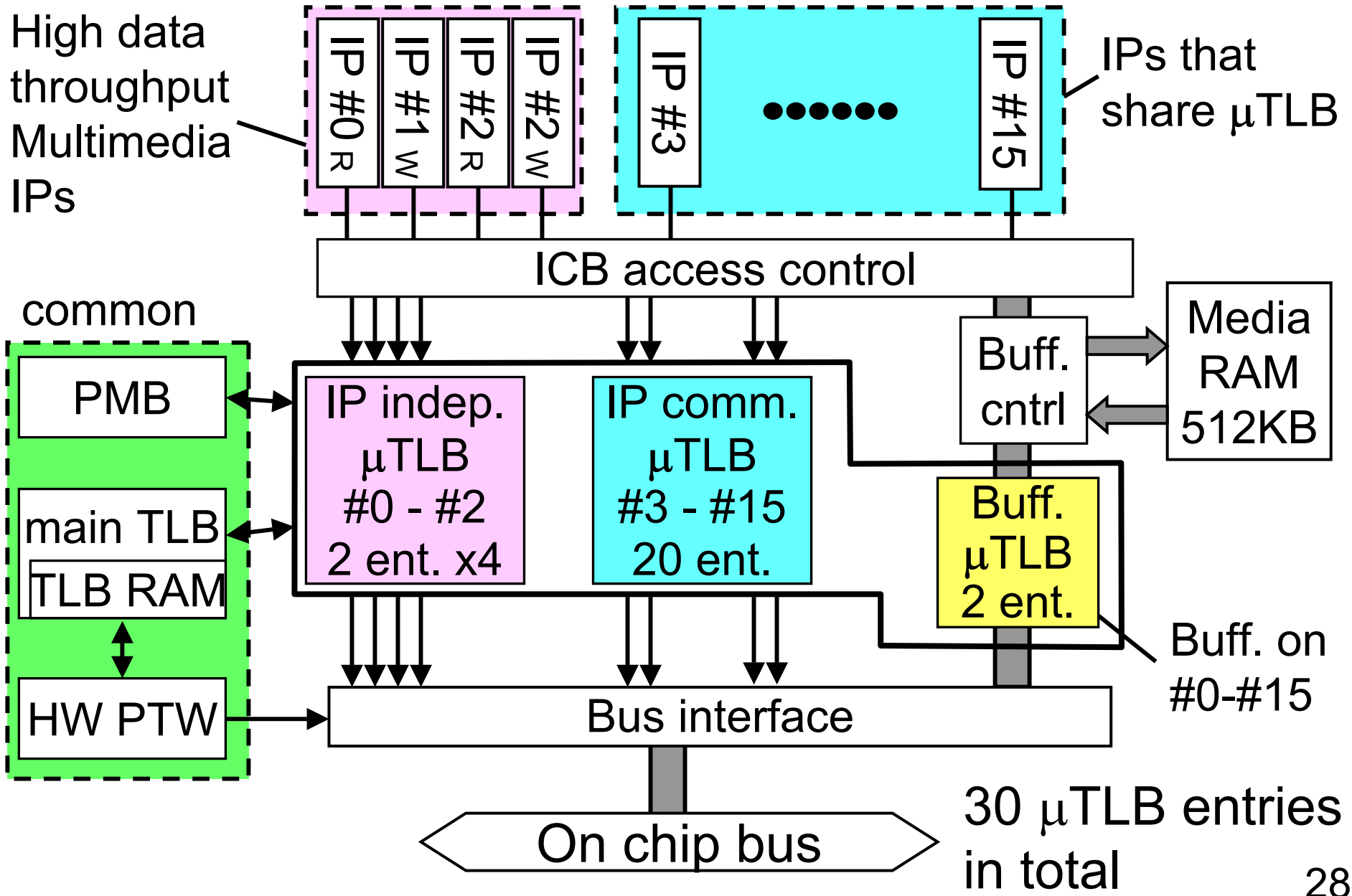
[Problem2]

Inserting IP-MMU to each IP side ⁽²⁾ is costly because 16 IP-MMUs are needed for ICB.



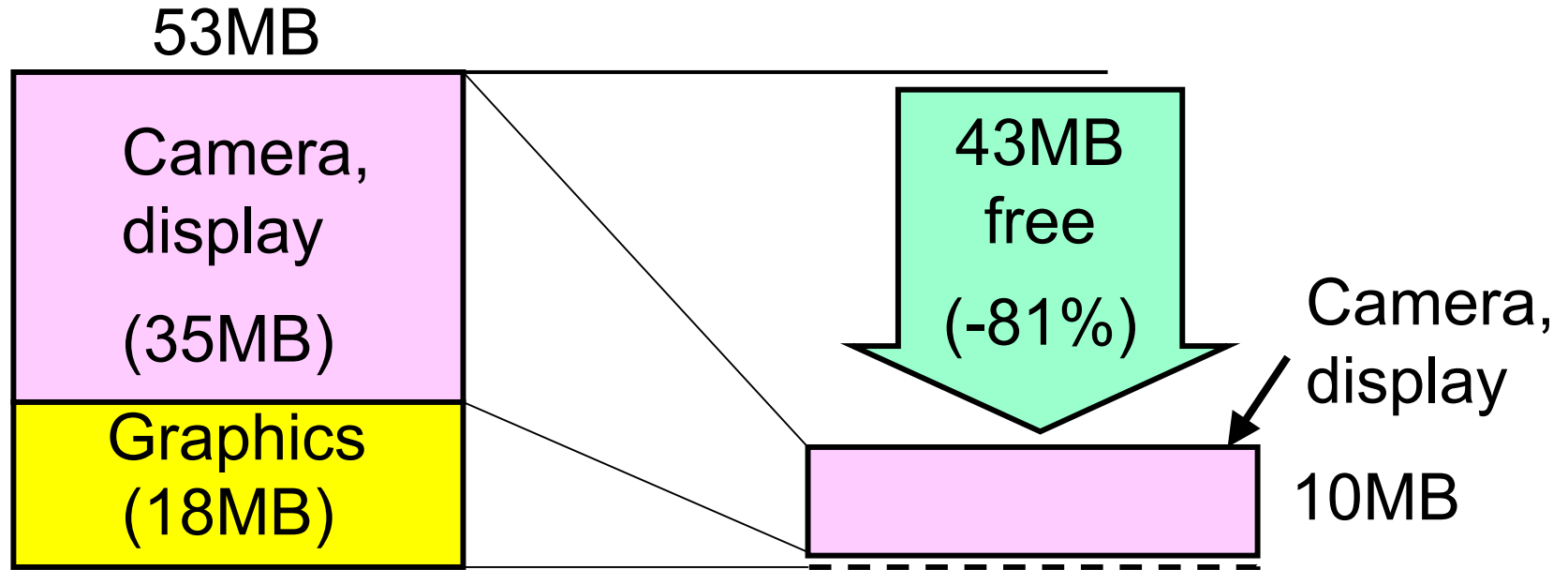
IP-MMU : Solution

High data throughput
Multimedia
IPs



IP-MMU: Evaluation results

- Statically allocated memory size



Note: All IP are used with IP-MMU.

- Performance evaluation

Degradation is negligible.

Video camcorder application performance:

30 fps @D1(720x520) for MPEG4/AVC format on G3

Summary

- The SH-Mobile G3 integrates a dual-mode (3G/2G) baseband processor, an application processor, and a multimedia processor with 65nm LP for mobile phone.
- Hierarchical Power Domain architecture separates the chip into 20 power domains and reduces leakage in many use cases.
- Partial Clock Activation reduces power even in low power scenario. It achieved more than 40% reduction of chip power in long time music replay scene.
- IP-MMU enables HW-IPs to use physically fragmented memory. By using this, more than 80% of statically allocated memory can be freed in the actual system without performance degradation.